





USB077A - PRELIMINARY

Band N77 USB Series TDD Bandpass Filter

Features

- Low Loss with High Rejection
- Low ripple
- Universal footprint across family for all TDD bands

Applications

- Wireless Infrastructure applications
- High-performance carrier-grade single-band TDD Pico-cell basestations for up to 5.0W at the antenna port.



Materials: Ag plated ceramic block with tin plated brass shield

Description

Surface mount ceramic bandpass filter supports a universal footprint across all TDD frequency bands enabling the use of a common system PCB. Superior rejection, insertion loss, reliability, as well as both peak and average power handling compared to other bandpass filter technologies.

Electrical Specifications

Parameter	Frequency (MHz)	Typical at 25°C	Spec. at 25°C	Spec. over -40°C to +85°C
Nominal Impedance	-	50 ohms	-	-
Average Input Power	-	-	-	8.0 Watt max
Peak Input Power	-	-	-	80 Watt max
Input-Output Response				
Passband Insertion Loss (20 MHz avg)	3300 - 4200	1.0 dB	1.1 dB max	1.2 dB max
Passband Ripple	3300 - 4200	0.5 dB	0.7 dB max	0.8 dB max
Passband Return Loss	3300 - 4200	14 dB	12 dB min	12 dB min
Attenuation:	1 - 2700	>60 dB	40 dB min	40 dB min
	5150 - 5950	47 dB	40 dB min	40 dB min

Note: CTS tests each unit to the critical specifications above. Subsequent audits may deviate due to repeatability among different test systems which shall not exceed these allowances.

Specification Allowance						
Insertion Loss	0.1 dB					
Return Loss	1.0 dB					
Attenuation	1.0 dB					

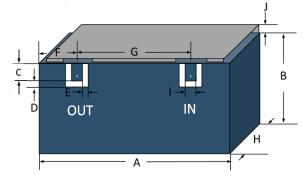
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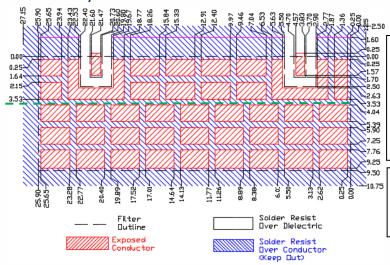
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Mechanical Drawing



Nominal Tolerance Dim. (±mm or Max) (mm) 25.90 Α max 2.50 В max C 1.70 0.13 D 0.40 0.13 E 0.80 0.13 F 4.20 0.13 G 16.90 0.13 Н 6.70 max 1 1.00 0.13 1.10 0.20

PCB Layout



IMPORTANT: Please assure >=30mils (0.75mm) thickness of dielectric beneath the I/O Pads <u>and</u> the surrounding clearance zone down to the ground plane.

Please assure sufficient ground vias between the top metal ground plane and the primary ground plane.

Recommended solder: 4-6 mils of SAC305 with reflow including 120s of soak at 217°C, and up to 30 sec peak at 241°C.

NOTE: The width of 9.50mm is necessary to support frequencies as low as 1885MHz for Band 39. If only higher frequency TDD bands are supported, then a smaller space can be allocated on the layout.

Packaging and Marking

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Dimensi	on Unit	ts Spec.	Product	Marking			
Reel Diam	eter mm	330		TS			
Reel Wei	ght kg	5.5	_	77			
Reel Quar	ntity ea.	500	YV	VW			
Customer Feed Direction $ ightarrow$							
Bo MM/(Inches) Po MM/(Inches) AO MM/(Inches)							
Wo	Ao	Во	Ko	Po			
1.732 in	0.165 in	1.028 in	0.283 in	0.472 in			
44.0 mm	4.20 mm	26.10 mm	7.20 mm	12.0 mm			

